



Express Mail No. EV336673758US

Attorney Docket No. 108298630US  
Disclosure No. 01-0532.00/US

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: SETHO SING FEE ET AL.  
APPLICATION NO.: 09/944,246  
FILED: 30 August 2001  
FOR: **PACKAGED MICROELECTRONIC  
DEVICES AND METHODS OF FORMING  
SAME**

EXAMINER: TU TU V. HO  
ART UNIT: 2818  
CONFIRMATION NO.: 1798

**Supplemental Information Disclosure Statement**  
**As Submission Under 37 CFR §1.114**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

1. Timing of Submission

This information disclosure is being filed with a Request for Continued Examination under 37 CFR §1.114. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

2. Cited Information

☒ Copies of the following references are enclosed:

- ☒ All cited references  
☐ The following:

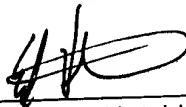
3. Effect of Information Disclosure Statement (37 CFR 1.97(h))

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

4. Fee Payment

No fees are believed due. However, should the Commissioner determine that fees are due in order for this Information Disclosure Statement to be considered, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 50-0665.

Respectfully submitted,  
Perkins Coie LLP



\_\_\_\_\_  
Edward S. Hotchkiss  
Registration No. 33,904

Date: 13 May 2004

**Correspondence Address:**

Customer No. 25096  
Perkins Coie LLP  
P.O. Box 1247  
Seattle, Washington 98111-1247  
Phone: (206) 359-8000



Express Mail No. EV336673758US

Attorney Docket No. 108298630US  
Disclosure No. 01-0532.00/US**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
Form PTO-1449 (Modified)  
(Use several sheets if necessary)**COMPLETE IF KNOWN**

Application Number	09/944,246
Confirmation Number	1798
Filing Date	30 August 2001
First Named Inventor	Setho Sing Fee
Group Art Unit	2818
Examiner Name	Tu Tu V. Ho
Attorney Docket No.	108298630US

Sheet 1 of 2

**U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
		U.S. Application No. 10/651,913 Attorney Docket No. 108298733US		Seng et al.	Filed 08/29/2003	
		5,107,328		Kinsman	04/21/1992	
		5,138,434		Wood et al.	08/11/1992	
		5,815,000		Farnworth et al.	09/29/1998	
		5,866,953		Akram et al.	02/02/1999	
		5,973,393		Chia et al.	10/26/1999	
		6,066,514		King et al.	05/23/2000	
		6,089,920		Farnworth et al.	07/18/2000	
		6,094,058		Hembree et al.	07/25/2000	
		6,228,687	B1	Akram et al.	05/08/2001	
		6,339,254	B1	Venkateshwaran et al.	01/15/2002	
		6,429,528	B1	King et al.	08/06/2002	
		6,501,184	B1	Shin et al.	12/31/2002	
		6,576,494	B1	Farnworth	06/10/2003	
		2004/0026773	A1	Koon et al.	02/12/2004	

**OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.	T
		ISHINO, Toshiaki, Silicone Adhesive Tape, Nitto Technical Report, Vol. 38, No. 2, pp. 49-50, December 2000, < <a href="http://www.nitto.com/rd/2000_2/15ishinoe.qxp.pdf">http://www.nitto.com/rd/2000_2/15ishinoe.qxp.pdf</a> >.	
		KUHNLEIN, Gerd, "A design and manufacturing solution for high reliable non-leaded CSP's like QFN," 2000 Electronics Packaging Technology Conference, pp. 169-175.	
		Tech Connect, QFN Leadframes, ASM Pacific Technology Ltd., pp. 10-14.	

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application(s).



Attorney Docket No. 108298630US  
Disclosure No. 01-0532.00/US

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

Form PTO-1449 (Modified)  
(Use several sheets if necessary)

**COMPLETE IF KNOWN**

Application Number	09/944,246
Confirmation Number	1798
Filing Date	30 August 2001
First Named Inventor	Setho Sing Fee
Group Art Unit	2818
Examiner Name	Tu Tu V. Ho
Attorney Docket No.	108298630US

Sheet 2 of 2

Siliconware Precision Industries Ltd., TSOP 1 (Thin Small Outline Package type1),  
2 pages, retrieved from the Internet on June 26, 2003, <<http://www.spil.com.tw/tsopi.html>>.

Intersil, L56.8X8 56 Lead Quad Flat No-Lead Plastic Package, 1 page, December 2002,  
<<http://www.intersil.com/data/pk/L56.8x8.pdf>>.

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and  
not considered. Include copy of this form with next communication to application(s).